

Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- A. Samsung Part Number

- Samsung P/N : CL05C100JC51PNC
 - CAP, 10pF, 100V, ±5%, C0G, 0402
- AEC-Q 200 Specified

• Description :

		CL ①	<u>05</u> ②	<u>C</u> 3	<u>100</u> ④	<u>J</u> 5	<u>C</u> 6	<u>5</u> ⑦	<u>1</u> ⑧	<u>P</u> 9	<u>N</u> 10	<u>C</u> 10		
1	Series Samsung Multi-layer Ceramic Capacitor													
2	Size	0402 (inch co	ode)		L:	1.0	± 0.05		mm		W:	0.5	± 0.05 mm	
3	Dielectric	C0G				8	Inner	electr	ode			Ni		
4	Capacitance	10 pF					Termi	natio	n			Cu		
5	Capacitance	±5 %					Platin	g				Sn 100%	(Pb Free)	
	tolerance					9	Produ	ct				Automotiv	ve	
6	Rated Voltage	100 V				10	Grade	code	•			Standard		
\bigcirc	Thickness	0.5 ± 0.05	mm			1	Packa	ging				Cardboar	d Type, 7" reel	

B. Reliablility Test and Judgement condition

	Performance	Test condition					
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150 °C					
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within ±2.5% or ±0.25 ${}_{\text{p}}\text{F}$ whichever is larger						
	Q : 600 min						
	IR : More than 10,000№ or 500№×μF						
	Whichever is Smaller						
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles					
	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within ±2.5% or ±0.25 ${}_{\text{p}}\text{F}$ whichever is larger	1 cycle condition :					
	Q : 600 min	-55+0/-3 ℃(15±3min) -> Room Temp(1min.)					
	IR : More than 10,000 M or 500 M $\times \mu F$	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)					
	Whichever is Smaller						
Destructive Physical	No Defects or abnormalities	Per EIA 469					
Analysis							
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle					
	Capacitance Change :	Heat (25~65 $^\circ\!\!\mathrm{C}$) and humidity (80~98%), Unpowered					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	measurement at 24±2hrs after test conclusion					
	Q : 300 min						
	IR : More than 10,000 M or $500 M \times \mu F$						
	Whichever is Smaller						
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 °C/85%RH, Rated Voltate and 1.3~1.5V,					
	Capacitance Change :	Add 100kohm resistor					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Measurement at 24±2hrs after test conclusion					
	Q : 133.33 min	The charge/discharge current is less than 50mA.					
	IR : More than 500 M or 25 M × μ F						
	Whichever is Smaller						
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 °C, 200% Rated Voltage,					
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within $\pm 3.0\%$ or ± 0.3 pF whichever is larger	The charge/discharge current is less than 50mA.					
	Q : 300 min						
	IR : More than 10,000№ or 500№×μF						
	Whichever is Smaller						

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope ('10)					
Physical Dimensions	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Peakvalue Duration Wave Velocity					
	Q, IR : initial spec.	1,500G 0.5ms Half sine 4.7m/sec.					
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,					
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side					
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted					
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000 $\rm Hz$.					
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 °C, 10±1sec.					
Solder Heat	Capacitance Change :						
	within ±2.5% or ±0.25 ${}_{\text{p}}{}^{\text{F}}$ whichever is larger						
	Q, IR : initial spec.						
Thermal Shock	Appearance : No abnormal exterior appearance	-55 °C/+125 °C.					
	Capacitance Change :	Note: Number of cycles required-300,					
	within ±2.5% or ±0.25 ${}_{\text{p}}\text{F}$ whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air					
	Q, IR : initial spec.						
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002					
	Capacitance Change :						
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger						
	Q, IR : initial spec.						
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245 \pm 5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260 \pm 5 $^\circ$ C					
		solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 $^\circ C$,					
Characterization	Q : 600 max.	1Mb±10%, 0.5~5Vrms					
	IR(25℃) : More than 100,000№ or 1,000№×μF	I.R. should be measured with a DC voltage not exceeding					
	IR(125 °C) : More than10,000 № or 100 № ×μF	Rated Voltage @25°C, @125°C for 60~120 sec.					
	Whichever is Smaller	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Board Flex	Dielectric Strength	Dending to the limit (2)) for 5 eccords					
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds					
	Capacitance Change :						
Terminal	within ±5.0% or ±0.5pF whichever is larger Appearance : No abnormal exterior appearance	2N, for 60±1 sec.					
Strength(SMD)	Capacitance Change :	21, 101 0021 300.					
	within $\pm 2.5\%$ or $\pm 0.25pF$ whichever is larger						
Beam Load	Destruction value should not be exceed	Beam speed					
_ sum _ sum	Chip Length < 2.5mm	0.5±0.05mm/sec					
	a) Chip Thickness > 0.5mm : 20N						
	b) Chip Thickness ≤ 0.5 mm : 20N						
Temperature							
Characterisitcs	(From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change shoud	be within ±30PPM/°C)					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.